

DESCRIPTION

~~METHOD FOR MANUFACTURING POLISHING HEAD, AND POLISHING~~ DEVICE

TECHNICAL FIELD

[0001]

The present invention relates to a method of producing a polishing head for holding a workpiece and a polishing apparatus including the polishing head.

BACKGROUND ART

[0002]

In production of semiconductor wafers such as silicon wafers, a polishing process is one of important processes to improve surface roughness and flatness of these wafers. As the precision of devices has recently been increased, there is an increasing need for more precisely flattened semiconductor wafers for use in device fabrication. According to this need, chemical mechanical polishing (CMP) is used as a technique to flatten a surface of semiconductor wafers.

[0003]

Apparatuses for polishing surfaces of a workpiece such as a silicon wafer may be classified into two types: a single-side polishing apparatus that polishes one of the surfaces of the workpiece at a time and a double-side polishing apparatus that polishes both the surfaces simultaneously.

In a conventional CMP process on a semiconductor wafer (also referred to as a wafer below) with a common single-side polishing apparatus, there is a method to hold an opposed surface to a surface to be polished of

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